



SSP-1405L

THERMAL CONDUCTIVE SILICONE LUBRICATING COMPOUND

PRODUCT DESCRIPTION

SSP-1405L is a medium-bodied thermal conductive, heat sink compound which is designed to meet the demanding applications that require excellent heat transfer. SSP-1405L features a useful application range of -70^oF to 450^oF, no bleed or separation and excellent dispersion and stability. SSP-1405L does not dry out, harden or melt.

DATA	TYPICAL VALUES
Appearance	White / Opaque
Temperature	-70 ^o F to 450 ^o F
Worked Penetration (300- 360 Range)	320
Unworked Penetration (260-320 Range)	275
Bleed (1.0% Max after 1 hour @ 200°C)	0.08%
Evaporation (0.5% Max after 1 hour @ 200°C)	0.20%
Specific Gravity (2.30 minimum)	2.38
Thermal Conductivity	2.9 BTU-in/hrft ²⁻⁰ F 0.0010 Cal/sec-cm ²⁻⁰ C 0.42 Watt/m-K

KEY FEATURES	APPLICATIONS	CONTAINERS
Designed to Meet MIL-C-47113 High Thermal Conductivity Low Bleed and Evaporation Water Resistant Excellent Dielectric Properties Chemically Inert Hydrolytically Stable	Mounting Studs of Transistors & Diodes Thermocouple Wells Shock & Heat Dissipation in Transistors Thermal Joints Mounting Semi-Conductive Devices Heat Transfer Medium & Ballast	400 lb Drum 40 lb Plastic Pail 8 lb. Plastic Pail 1 lb Jar 14.1 oz Cartridge 5.3 oz Plastic Tube

Private labeling & specialty packaging are always available to meet customers' total requirements.

HANDLING & SAFETY

MSDS information is available on request.

For more information visit www.sspinc.com. To order call (518) 885-8826/ or Fax (518) 885-4682.

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